Abstracts

Time Domain Analysis of via Holes and Shorting PINs in Microstip Using 3-D SCN TLM

C. Eswarappa and W.J.R. Hoefer. "Time Domain Analysis of via Holes and Shorting PINs in Microstip Using 3-D SCN TLM." 1993 MTT-S International Microwave Symposium Digest 93.2 (1993 Vol. II [MWSYM]): 917-920.

The scattering parameters of microstrip via holes and shorting pins have been computed using 3-D SCN TLM method. The results agree well with the available data, thus demonstrating that the TLM method is a powerful tool applicable in the analysis of monolithic microwave integrated circuits of high density and high speed digital microwave circuits.

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